

ABSTRACT

A dicing/die bonding integrated film according to an aspect of the present disclosure has a configuration in which at least a base layer, a pressure-sensitive adhesive layer, and an adhesive layer are sequentially stacked, and the pressure-sensitive adhesive layer contains a photopolymerization component and a photopolymerization initiator (D). The photopolymerization component includes a structural unit derived from a polymer (A) having a group containing a quaternary ammonium salt and a hydroxyl group, an energy curable pressure-sensitive adhesive component (B) having a hydroxyl group, and a thermal cross-linking agent (C), and the structural unit is at least one of a structural unit in which the polymer (A) and the pressure-sensitive adhesive component (B) are linked with each other via the thermal cross-linking agent (C) and a structural unit in which the pressure-sensitive adhesive components (B) are linked with each other via the thermal cross-linking agent (C).

Fig. 1